

”あったらいいな”がありました

OKUHARA
Ideas into ideal

Product Catalog



Here is “something useful” for your needs from mount related devices to production tools

We commit to offer continuous support from product development to maintenance and build solid credence with our clients.

Mount devices

Manual cream solder printer ST-310F



- Ideal for test/small quantity production
- Xy θ micro adjustment
- Special suction base installable
- Special order available for large board
- Easy operation
- Low cost

Cream solder printer with guide ST-310F1G



- Print pressure and angle can be fixed to device
- Reciprocate printing available
- Usable for 0603, 0.5 pitch printing
- Xy θ micro adjustment
- Ideal for small/medium quantity production
- Can be used together with StatLoc

Multi function mounter SMT-64RH



- Wide range for 0402~QFP
- board size: maximum M size (may vary according to layout)
- Displacement sensor or pressure detection installable
- Soldering ball or flux copy available
- Ideal for test production or R&D
- Side observation available

Mult robo station MRS-850



- Operates 3 process of dispense/mount/heat continuously
- Board size: max 150×200mm
- Spec for conveyer available
- Ideal for small/medium quantity production
- Ideal for small parts board like FPC or LED

Static IR Reflow furnace SAR-500A/500N



- Usable for lead free, high temperature soldering
- Board size: ~250×330mm
- Side observation
- Ideal for small/medium quantity production
- Easy profile creation using auto tuning function

Reflow analyzer VISTA7



- Simultaneous observation from top/beveled/side
- Board size : □100mm
- Usable for lead free, high temperature soldering
- Combined use of hot air/IR heater
- Easy profile creation using auto tuning function
- Ideal for test production or R&D

Reflow simulator Realar



- Simultaneous observation from top and side
- Board side : □50mm
- Usable for lead free/high temperature soldering
- Easy profile creation using auto tuning function
- Low cost

Board backup pin alignment device @PIN-Setter



- Shortens setup change time
- Easy operation
- Zigzag alignment
- Low cost

Mount production tools

Non-contact pencil reflow **APR-10**



- Stable heating of micro parts (Heating time: approx 5 seconds)
- Simple lever operation
- Easy positioning using laser illumination
- Xy θ micro adjustment

Reward tool for microchip **SEC-30**



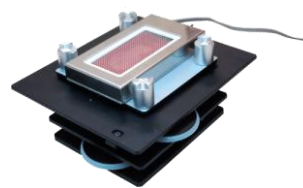
- Integration of 3 processes of remove/dispense/heat
- Usable for micro parts
- Head slide method enables each operation without moving board.
- Xy θ micro adjustment

IR Heater **PR-300**



- IR heating
- Profile control available
- Free heating position setting
- Maximum heating temperature: \square 30mm
- Can be used together with bottom heater

XY stage **PWS-20**



- Fixes board and achieves micro positioning
- XY θ displacement
- Supplementary bottom heater settable
- Low cost

Temporal pilot hole mask pin **Thru Hole Protector**



- Made of high-temperature resin for repeated use (over 100 times)
- Can be cut anywhere you like
- Simple operation
- Available in 6 types

Board warp preventing tool **Dipcover**



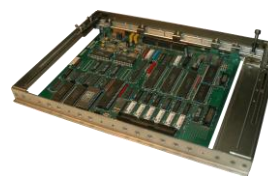
- Prevents warp and soldering overflow
- Protects parts placed on edge of board
- Usable repetitively (over 200 times)
- Custom order available

Soldering iron cleaner **Clean-O-Point (Elvo)**



- Cleans soldering iron quickly
- Cleaning prevents solder leak or bridge

Changeable dip carrier **AC300**



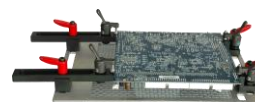
- Minimizes line-set time considerably
- Prevents soldering overflow and soldering touch to overhung parts simultaneously
- One-touch board attachment
- Made of titanium for lightweight
- Optional request acceptable

Board warp prevention tool **StatLoc**



- Prevents board warping on printer or mounter
- Detects parts mounted area automatically
- Minimizes setup time substantially

Warp-prevent pin alignment tool **SetLoc**



- Easy attachment
- Visual pin positioning
- Outer setup possible
- Low cost

■ ST-310F spec.

Work size	Maximum 250×310mm
Mask frame size	250×250~450×450mm
Plate adjustmet (X,Y,θ)	X/Y :±4.5mm θ :±2°
Plate removal	Manual front opening/closing style
Squeegee	Width:240mm Hardness level: approximately 90
Outer size (except balancer)	Width 360mm Depth 560mm Height 120mm/WT 23 kg

■ SMT-64RH spec.

Board size [mm]	MAX W250 ×D330 H 1.0~2.5 (may vary according to layout)
Mount accuracy	±40 [μm]
Mountable parts	0402~□30mm parts, SOP, QFP, CSP, BGA, soldering ball
Parts supply method	Chip stick, Supply stage, Palette, Tape feeder
Alignment method	Auto image processing, Stage alignment, Bottom camera alignment
Outer size [mm]	Length:740 × Width:700 × Height 600 [mm]

■ SAR500A/500N spec.

Maximum board size	250×330mm t=0.8~3.6mm
Board height	Top:25mm Bottom:15mm
Max heating temperature	400°C
Temperature accuracy	Under direct control, ±1dge of ±2.5% or ±5°C of set temperature whichever is larger
Temperature distribution	±5°C within □200mm inside of □250mm board
Temperature control	Auto tuning style
Power supply	AC200V 3φ / approximately 10kw (50~60Hz)
Air supply	Atmosphere:0.4~0.7MPa (50ℓ/min) / N2:00ℓ/min
Outer size [mm] / WT [kg]	Length:695×Width:1035×Height 690 [mm] / approximately 110 [kg]

■ Realar spec.

Maximum board size	50×50mm t=0.8~3.6mm
Max heating temperature	400°C
Temperature accuracy	Under direct control, ±1dge of ±2.5% or ±5°C of set temperature whichever is larger
Temperature distribution	±5°C within □200mm inside of □250mm board
Heat source	Top: heat air (circulating air) Bottom: IR Heater
Temperature control	Auto tuning style
Power supply	AC200V 3φ / approximately 3.5kw (50~60Hz)
Air supply	Atmosphere :0.4~0.7MPa (50ℓ/min) /N2:00ℓ/min

■ APR-10 spec.

Heating method	Heat air method (80w)
Max heating temperature	265 [°C]
Heating range	Chip 0402~□3mm
Heating time	5~6 seconds (may vary according to board)
Power	AC100V / 500w
Outer size [mm]	400×280×270 [mm]

■ ST-310F1G spec.

Work size	Maximum 250×310mm
Mask frame size	250×250~450×450mm
Plate adjustment (X,Y,θ)	X/Y :±4.5mm θ :±2°
Plate removal	Manual front opening/closing style
Squeegee	Width:240mm Hardness level: approximately 90
Outer size (except balancer)	Width 360mm Depth 560mm Height 120mm/WT 23kg

■ MRS-850 spec.

Board size [mm]	MAX W250 ×D150 H 0.8~2.5
Mount accuracy	±80 [μm]
Mountable parts/Supply method	1005~□8mm parts/Chip stick, Tape feeder
Alignment method	Collet, Mechanical centering stage
Heating method	Micro hot air heating
Dispense method	Commercially available dispense controller (outer signal control)
Outer size [mm]	Length:740×Width:700× Height 600 [mm]

■ VISTA7 spec.

Maximum board size	80×80mm t=0.8~3.6mm
Board height	Top:25mm
Max heating temperature	400°C
Temperature accuracy	Under direct control, ±1dge of ±2.5% or ±5°C of set temperature whichever is larger
Temperature distribution	±5°C within □80mm inside of □100mm board
Temperature control	Auto tuning style
Power supply	AC200V 3φ / approximately 7.8kw (50~60Hz)
Air supply	Atmosphere:0.4~0.7MPa (50ℓ/min) /N2:00ℓ/min
Outer size [mm]	Length:600 × Width:880 × Height 520 [mm]

■ PIN-Setter spec.

Maximum board size	250×250mm (optional: M size)
Number of pins	30 pins
Pin block	Size : 190×50×40 [mm] Number of grid : 16×5 points Grid pitch : 10×10mm
Control	PC control (OS: WindowsXP)
Air supply	Atmosphere:0.4~0.7MPa
Power supply	AC100V / 0.6 [KVA]
Main body size	Width:500 Depth:500 Height 480mm / 15kg

■ SEC-30 spec.

Parts removal mechanism	Tweezers type (30w) / Up-and-down: lever, Opening-closing: dial
Heating mechanism	Hot air method
Dispense mechanism	Up-and-down lever control / Control: commercially available controller
Maximum board size	120×300mm
Power	AC100V
Outer size [mm]	320×360×330 [mm]

※Above specification is subject to change in accordance with functional improvement.

OKUHARA
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